

L	Hits	Search Text	DB	Time stamp
Number				
1	326627	wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:06
2	240150	((chip semiconductor ic die (integrated adj circuit)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:08
3	193511	((chip semiconductor ic die (integrated adj circuit)) same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:08
4	42430	((chip semiconductor ic die (integrated adj circuit)) and wafer) and (testing test nontest (non adj test))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:09
5	15481	((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:10
6	94	(redistribute redistribution redistributed redistributing distribute) same ((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:12

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5	15481	((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:55
6	94	(redistribute redistribution redistributed redistributing distribute) same (((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:12
7	5685	((((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test))) and (offset external))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:56
8	2279	(((((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test))) and (offset external)) and (trace wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:56
9	2279	(((((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test))) and (offset external)) and (trace wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:57
10	1344	(((((chip semiconductor ic die (integrated adj circuit)) same wafer) same (testing test nontest (non adj test))) and (offset external)) and (trace wiring)) and (insulating sealing resin encapsulation encapsulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 14:04